

PATENT ASSIGNMENT COVER SHEET

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Stylesheet Version v1.2

EPAS ID: PAT3525660

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
ZVI OR-BACH	08/12/2015
DEEPAK SEKAR	08/17/2015
BRIAN CRONQUIST	08/12/2015
ZEEV WURMAN	08/08/2015
ISRAEL BEINGLASS	08/12/2015
RECEIVING PARTY DATA	
Name:	Monolithic 3D Inc.
Street Address:	3555 Woodford Drive
City:	San Jose
State/Country:	CALIFORNIA
Postal Code:	95124
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14821683
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Email:	Brian@Monolithic3D.com
Correspondent Name:	BRIAN CRONQUIST
Address Line 1:	3555 WOODFORD DRIVE
Address Line 4:	SAN JOSE, CALIFORNIA 95124
ATTORNEY DOCKET NUMBER:	MONOLITHIC3D-15CON2-CD
NAME OF SUBMITTER:	BRIAN CRONQUIST
SIGNATURE:	/bc/
DATE SIGNED:	09/15/2015
Total Attachments: 5	
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ASSIGNMENT

Whereas, I, **Zvi Or-Bach (hereinafter referred to as Assignor(s)), residing in San Jose, California;** have made a certain invention, and executed United States Patent Application entitled:

Novel 3D Semiconductor Device and Structure

as described in U.S. Patent Application Serial No. 14/821,683 and filed on August 07, 2015;
and

Whereas, **MonolithIC 3D™ Inc.**, a company located at 3555 Woodford Drive, San Jose, California 95124 (hereinafter called "Assignee"), desires to acquire the entire right, title, and interest in the application and the invention, and to any applications, patents and/or utility model registrations filed or obtained therefor in every Country (hereinafter called the "Designated Countries").

Now therefore, for valuable consideration, receipt of which is hereby acknowledged,

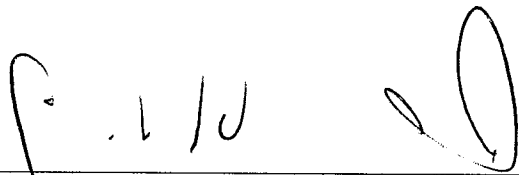
I/we, the above named Assignor(s), hereby sell, assign and transfer to the above named Assignee the entire right, title and interest to file and/or obtain any applications, patents and/or utility model registrations in the Designated Countries as regards the United States application and the invention disclosed therein (including rights of priority based on the United States application), and I/we will execute without further consideration all papers deemed necessary by the Assignee in connection with such applications, patents and/or utility model registrations in the Designated Countries when called upon to do so by the Assignee.

Signed and Sealed:

INVENTOR:

DATE on

8-12-15



(Zvi **Or-Bach)**
 First Name Middle Initial Last Name

ASSIGNMENT

Whereas, I, **Deepak Sekar** (hereinafter referred to as Assignor(s)), residing in **San Jose, California**; have made a certain invention, and executed United States Patent Application entitled:

Novel 3D Semiconductor Device and Structure

as described in U.S. Patent Application Serial No. 14/821,683 and filed on August 07, 2015;
and

Whereas, MonolithC 3D™ Inc., a company located at 3555 Woodford Drive, San Jose, California 95124 (hereinafter called "Assignee"), desires to acquire the entire right, title, and interest in the application and the invention, and to any applications, patents and/or utility model registrations filed or obtained therefor in every Country (hereinafter called the "Designated Countries").

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I/we, the above named Assignor(s), hereby sell, assign and transfer to the above named Assignee the entire right, title and interest to file and/or obtain any applications, patents and/or utility model registrations in the Designated Countries as regards the United States application and the invention disclosed therein (including rights of priority based on the United States application), and I/we will execute without further consideration all papers deemed necessary by the Assignee in connection with such applications, patents and/or utility model registrations in the Designated Countries when called upon to do so by the Assignee.

Signed and Sealed:

INVENTOR:

DATE on 17th Aug 2015

Deepak C Sekar

(Deepak

Sekar)

First Name

Middle Initial

Last Name

ASSIGNMENT

Whereas, I, **Brian Cronquist (hereinafter referred to as Assignor(s)), residing in San Jose, California;** have made a certain invention, and executed United States Patent Application entitled:

Novel 3D Semiconductor Device and Structure

as described in U.S. Patent Application Serial No. 14/821,683 and filed on August 07, 2015;

and

Whereas, **MonolithC 3D™ Inc.**, a company located at 3555 Woodford Drive, San Jose, California 95124 (hereinafter called "Assignee"), desires to acquire the entire right, title, and interest in the application and the invention, and to any applications, patents and/or utility model registrations filed or obtained therefor in every Country (hereinafter called the "Designated Countries").

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Signed and Sealed:

INVENTOR:

DATE on

12 Aug 2015



(Brian

Cronquist)

First Name

Middle Initial

Last Name

PATENT

REEL: 036562 FRAME: 0528

ASSIGNMENT

Whereas, I, **Zeev Wurman** (hereinafter referred to as Assignor(s)), residing in **Palo Alto, California**; have made a certain invention, and executed United States Patent Application entitled:

Novel 3D Semiconductor Device and Structure

as described in U.S. Patent Application Serial No. 14/821,683 and filed on August 07, 2015;
and

Whereas, **MonolithIC 3D™ Inc.**, a company located at 3555 Woodford Drive, San Jose, California 95124 (hereinafter called "Assignee"), desires to acquire the entire right, title, and interest in the application and the invention, and to any applications, patents and/or utility model registrations filed or obtained therefor in every Country (hereinafter called the "Designated Countries").

Now therefore, for valuable consideration, receipt of which is hereby acknowledged,

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Signed and Sealed:



INVENTOR:

DATE on 12/8/15

(Zeev			Wurman)
First Name	Middle Initial		Last Name

ASSIGNMENT

Whereas, I, **Israel Beinglass (hereinafter referred to as Assignor(s)), residing in San Jose, California;** have made a certain invention, and executed United States Patent Application entitled:

Novel 3D Semiconductor Device and Structure

as described in U.S. Patent Application Serial No. 14/821,683 and filed on August 07, 2015;
and

Whereas, **Monolithic 3D™ Inc.**, a company located at 3555 Woodford Drive, San Jose, California 95124 (hereinafter called "Assignee"), desires to acquire the entire right, title, and interest in the application and the invention, and to any applications, patents and/or utility model registrations filed or obtained therefor in every Country (hereinafter called the "Designated Countries").


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Signed and Sealed:

INVENTOR:

DATE on 8/12/13



(Israel	Beinglass)	
First Name	Middle Initial	Last Name